

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) ~~A two-component~~ Two-component adhesive **K**, comprising: ~~of~~

\_\_\_\_\_ a component **K1** and a component **K2**, ~~characterized in that~~ wherein:

\_\_\_\_\_ (a) ~~the~~ component **K1** comprises:

at least one epoxy resin ~~A with~~ having more than one epoxy group per molecule ~~on the average;~~

at least one epoxy adduct **B**, wherein each epoxy adduct **B** with has more than one epoxy group and more than one hydroxyl group per molecule ~~on the average;~~

at least one product **F** of a reaction between an epoxy adduct **B** and a compound **C** with at least two isocyanate ~~groups,~~ groups; and

at least one curing agent **D** for epoxy resins, which is activated by elevated temperature;

\_\_\_\_\_ and

(b) ~~the~~ component **K2** comprises:

\_\_\_\_\_ at least one compound **E** with at least two isocyanate groups;

wherein:

\_\_\_\_\_ ~~and where the epoxy adduct **B** is an epoxy adduct **B1**, which can be obtained~~ from at least one dicarboxylic acid and at least one diglycidyl ether;

\_\_\_\_\_, ~~and is optionally combined with an epoxy adduct **B2**, which can be obtained~~ from at least one bis(aminophenyl)sulfone isomer or at least one aromatic alcohol and at least one diglycidyl ether.

2. (Currently Amended) ~~Two-component adhesive **K** as in Claim 1,~~ characterized in that The adhesive according to claim 1, wherein the epoxy resin **A** is a liquid resin; resin, in particular a bisphenol **A** diglycidyl ether, bisphenol **F** diglycidyl ether, or bisphenol **A/F** diglycidyl ether.

3. (Currently Amended) ~~Two-component adhesive **K** as in Claim 1 or Claim 2,~~ characterized in that The adhesive according to claim 1, wherein for preparation of the epoxy

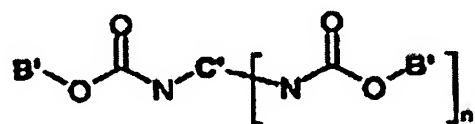
adduct ~~B1~~, the dicarboxylic acid is a dimeric fatty acid, in particular at least one dimeric C4-C20 fatty acid, is used as the dicarboxylic acid, and the diglycidyl ether is selected from the group consisting of bisphenol A diglycidyl ether, bisphenol F diglycidyl ether, or and bisphenol A/F diglycidyl ether is used as the diglycidyl ether.

4. (Currently Amended) ~~Two component adhesive K as in any one of the preceding claims, characterized in that~~ The adhesive according to claim 1, wherein:  
\_\_\_\_\_ for preparation of the epoxy adduct B2 is prepared from at least one aromatic alcohol and at least one diglycidyl ether,  
\_\_\_\_\_ an the aromatic alcohol is used that is selected from the group consisting of  
 2,2-bis(4-hydroxyphenyl)propane, bis(4-hydroxyphenyl)methane, bis(4-hydroxyphenyl)sulfone, hydroquinone, resorcinol, pyrocatechol, naphthohydroquinone, naphthoresorcinol, dihydroxynaphthalene, dihydroxyanthraquinone, dihydroxybiphenyl, 3,3-bis(*p*-hydroxyphenyl)phthalide, 5,5-bis(4-hydroxyphenyl)hexahydro-4,7-methanoindane, as well as all and isomers thereof of the aforementioned compounds; and  
\_\_\_\_\_ the diglycidyl ether is selected from the group consisting of bisphenol A diglycidyl ether, bisphenol F diglycidyl ether, or and bisphenol A/F diglycidyl ether is used as the diglycidyl ether.

5. (Currently Amended) ~~Two component adhesive K as in any one of the preceding claims, characterized in that~~ The adhesive according to claim 1, wherein epoxy adduct B has a molecular weight of 700-6000 g/mol, preferably 900-4000 g/mol, in particular 1000-3300 g/mol.

6. (Currently Amended) ~~Two component adhesive K as in any one of the preceding claims, characterized in that~~ The adhesive according to claim 1, wherein the compound C is a polyurethane prepolymer C2 having isocyanate groups, which is synthesized from at least one polyisocyanate C1 and from at least one polyol, in particular at least one polyoxyalkylene polyol, preferably at least one polyoxyalkylene diol.

7. (Currently Amended) ~~Two component adhesive K as in any one of the preceding claims, characterized in that~~ The adhesive according to claim 1, wherein the reaction product F has the structure



\_\_\_\_\_ wherein **B'** is structurally identical to epoxy adduct B, except one hydroxyl groups is missing, and wherein **C'** is structurally identical to compound C, except all the isocyanate groups are missing, and wherein  $n+1$  represents the number of isocyanate groups in compound C.

8. (Currently Amended) ~~Two-component adhesive K as in any one of the preceding claims, characterized in that~~ The adhesive according to claim 1, wherein that the curing agent D is a latent curing agent selected from the group consisting of dicyanodiamide, guanamine, guanidine, and aminoguanidine.

9. (Currently Amended) ~~Two-component adhesive K as in any one of the preceding claims, characterized in that~~ The adhesive according to claim 1, wherein the compound E is a polyisocyanate or a polyurethane prepolymer having isocyanate groups, which is synthesized from at least one polyisocyanate and from at least one polyol, in particular at least one polyoxyalkylene polyol, preferably at least one polyoxyalkylene diol.

10. (Currently Amended) ~~Two-component adhesive K as in any one of the preceding claims, characterized in that~~ The adhesive according to claim 1, wherein a the total proportion of epoxy resin A and epoxy adduct B together is 10-60 wt.%, preferably 15-55 wt.%, based on the a total weight of the total adhesive K.

11. (Currently Amended) ~~Two-component adhesive K as in any one of the preceding claims, characterized in that~~ The adhesive according to claim 1, further comprising at least one filler additionally at least one filler is present, in particular in a proportion of 5-30 wt.%, preferably 10-25 wt.%, based on the a total weight of the total adhesive K.

12. (Currently Amended) ~~Two-component adhesive K as in any one of the preceding claims, characterized in that~~ The adhesive according to claim 1, further comprising additionally at least one reactive diluent with epoxy groups is present.

13. (Currently Amended) ~~Method A method~~ for fabrication of a semifinished product H using the adhesive according to claim 1, characterized in that comprising:  
heating at least the component K1 is heated to a temperature between 130°C and 60°C, in particular between 130°C and 80°C, preferably between 100°C and 90°C;  
mixing together the components K1 and K2; are mixed together, and  
applying the mixed adhesive K as in any one of Claims 1 to 12 is applied to a flat substrate S1; and then the

~~\_\_\_\_\_ contacting the adhesive K on substrate S1 is brought into contact with a flat substrate S2, in particular with application of pressure to at least one of substrates S1 or S2 during or after contact is made with substrate S2, so that the mixed adhesive K is placed between substrates S1 and S2.~~

14. (Currently Amended) ~~Method for fabrication of a semifinished product H as in Claim 13, characterized in that~~ The method according to claim 13, wherein the flat substrate S1 consists of the same material as the flat substrate S2.

15. (Currently Amended) ~~Method for fabrication of a semifinished product H as in Claim 13 or Claim 14, characterized in that~~ The method according to claim 13, wherein at least one of substrates S1 or S2 is sheet metal, in particular steel sheet or aluminum sheet, preferably oiled steel sheet or oiled aluminum sheet, where oiled steel sheet is particularly preferred.

16. (Currently Amended) ~~Method for fabrication of a semifinished product H as in Claim 15, characterized in that~~ The method according to claim 15, wherein the sheet metal has a thickness between 0.5 mm and 0.1 mm, in particular between 0.4 mm and 0.2 mm.

17. (Currently Amended) ~~Method for fabrication of a semifinished product H as in any one of Claims 13 to 16, characterized in that~~ The method according to claim 13, wherein the components K1 and K2 are mixed in such a ratio that the OH/NCO ratio is  $\geq 2$ , in particular 2-50, is  $\geq 2:1$ .

18. (Currently Amended) ~~Method for fabrication of a semifinished product H as in any one of Claims 13 to 17, characterized in that~~ The method according to claim 13, wherein the semifinished product H is subsequently coiled into a roll and stored in the form of a coil;

~~\_\_\_\_\_ or~~  
~~\_\_\_\_\_ is cut to length and the semifinished product H, cut to length, is stored in the form of a stack.~~

19. (Currently Amended) ~~Semifinished product H, characterized in that it is fabricated by a method as in any one of Claims 13 to 18.~~ The semifinished product H fabricated according to the method of claim 13.

20. (Currently Amended) ~~Method~~ A method for fabrication of a sandwich composite S, characterized in that a ~~wherein the semifinished product H as in~~ according to

Claim 19 undergoes a forming process and is heated to a temperature between 130°C and 230°C, ~~in particular between 170°C and 190°C.~~

21. (Currently Amended) ~~Sandwich composite S, characterized in that it is fabricated according to a method as in Claim 20.~~ The sandwich composite S fabricated according to claim 20.

22. (Currently Amended) ~~Use of a sandwich composite S as in Claim 21, characterized in that it is used in automotive assembly, in particular in auto body assembly.~~ An automotive assembly composite, comprising the sandwich composite S according to claim 21.

23. (New) The adhesive according to claim 1, wherein epoxy resin **A** is a liquid resin selected from the group consisting of bisphenol A diglycidyl ether, bisphenol F diglycidyl ether, and bisphenol A/F diglycidyl ether.

24. (New) The adhesive according to claim 3, wherein the dicarboxylic acid is a dimeric C4-C20 fatty acid.

25. (New) The adhesive according to claim 1, wherein epoxy adduct **B** has a molecular weight of 900-4000 g/mol.

26. (New) The adhesive according to claim 1, wherein epoxy adduct **B** has a molecular weight of 1000-3300 g/mol.

27. (New) The adhesive according to claim 6, wherein the polyol is a polyoxyalkylene polyol.

28. (New) The adhesive according to claim 6, wherein the polyol is a polyoxyalkylene diol.

29. (New) The adhesive according to claim 9, wherein the polyol of compound **E** is a polyoxyalkylene polyol.

30. (New) The adhesive according to claim 9, wherein the polyol of compound **E** is a polyoxyalkylene diol.

31. (New) The adhesive according to claim 1, wherein a total proportion of epoxy resin **A** and epoxy adduct **B** together is 15-55 wt.% based on a total weight of adhesive **K**.

32. (New) The adhesive according to claim 1, further comprising at least one filler in a proportion of 10-25 wt.% based on a total weight of adhesive **K**.

33. (New) The method according to claim 13, wherein:

the step of contacting the adhesive **K** on substrate **S1** with a flat substrate **S2** further comprises applying pressure to at least one of substrates **S1** or **S2** during or after contact is made with substrate **S2**.

34. (New) The method according to claim 15, wherein the sheet metal is steel sheet or aluminum sheet.

35. (New) The method according to claim 34, wherein the sheet metal is oiled.

36. (New) The method according to claim 15, wherein the sheet metal has a thickness between 0.4 mm and 0.2 mm.

37. (New) The method according to claim 13, wherein components **K1** and **K2** are mixed in such a ratio that the OH/NCO ratio is 2:1 to 50:1.

38. (New) A method for fabrication of a sandwich composite **S**, wherein the semifinished product **H** according to Claim 19 undergoes a forming process and is heated to a temperature between 170°C and 190°C.

39. (New) The method according to claim 13, wherein component **K1** is heated to a temperature between 130°C and 80°C.

40. (New) The method according to claim 13, wherein component **K1** is heated to a temperature between 100°C and 90°C.